

Amendments to the Claims:

1. (currently amended) A method for securing a flexible printed circuit board to an aluminum rigidizer that serves as a heat sink, the method comprising steps of:  
~~milling vents into the printed circuit board;~~  
applying a liquid adhesive to the aluminum rigidizer;  
applying a first cure to selected areas of the liquid adhesive after application of the liquid adhesive to produce a liquid adhesive that is at least partially cured in the selected areas, wherein the first cure of the liquid adhesive produces a tacky adhesive;  
placing the printed circuit board on the at least partially cured liquid adhesive and pressing the board onto the adhesive to provide a thermal path between the housing and the rigidizer;  
screening a solder paste onto the printed circuit board;  
placing components onto the solder paste on the printed circuit board; and  
applying a second heat cure to the assembly of the components, printed circuit board, solder paste, at least partially cured adhesive, and rigidizer, wherein the applied heat reflows the solder paste to bond the components to the printed circuit board while simultaneously providing a the second cure, ~~facilitated by the vents,~~ to the at least partially cured liquid adhesive to produce a printed circuit board that is secured to the aluminum rigidizer; and  
bending the printed circuit board and the aluminum rigidizer after the second cure of the at least partially cured liquid adhesive.
2. (previously presented) The method of claim 1, wherein the step of applying the liquid adhesive to the aluminum rigidizer comprises a step of screening the liquid adhesive onto the aluminum rigidizer.
3. (cancel).
4. (original) The method of claim 1, wherein the liquid adhesive is a dual-cure system adhesive.
5. (original) The method of claim 4, wherein the liquid adhesive is a B-stage epoxy.

6. (cancelled)

7. (cancel)

8-10. (cancelled)

11. (withdrawn) The method of claim 1, wherein the liquid adhesive can be cured by exposure to ultraviolet radiation.

12. (withdrawn) The method of claim 1, wherein the liquid adhesive can be cured by any one of a plurality of curing methods, wherein the first cure comprises applying a first curing method of the plurality of curing methods to the liquid adhesive and wherein the second cure comprises applying a second, different curing method of the plurality of curing methods to the liquid adhesive.

13-26. (cancelled)

27. (withdrawn) The method of claim 21, wherein the liquid adhesive can be cured by exposure to ultraviolet radiation.

28. (withdrawn) The method of claim 21, wherein the liquid adhesive can be cured by any one of a plurality of curing methods, wherein the first cure comprises applying a first curing method of the plurality of curing methods to the liquid adhesive and wherein the second cure comprises applying a second, different curing method of the plurality of curing methods to the liquid adhesive.